

# SML12R3KIR941T-TR

Red/Infrared

Surface Mount LED

3.2 × 2.7 × 1.85 mm Chip LED

120° viewing angle

DWG BY:  
SL / GP  
03-19-07

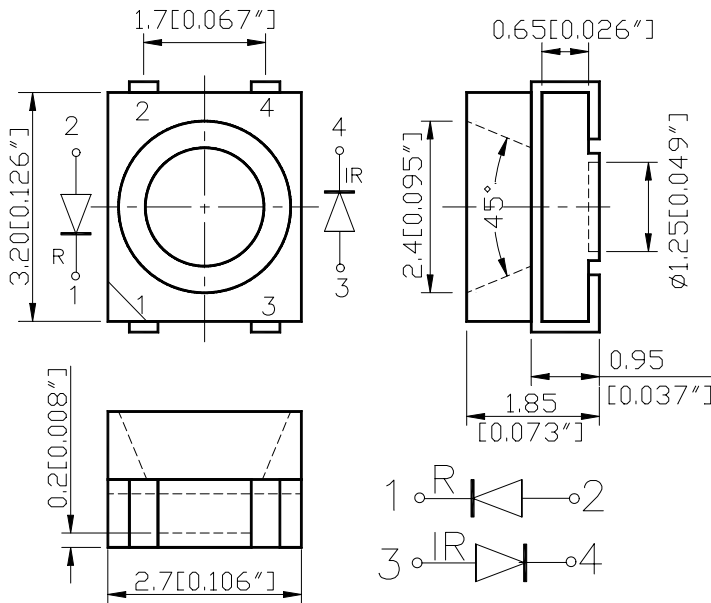
CHK BY:  
PL  
03-20-07

QA:  
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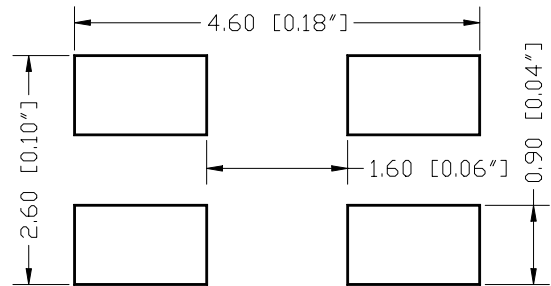
MFG:  
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REVISION LTR: -  
03-19-07

## Package outlines



### RECOMMEND PAD LAYOUT



ITEM	MATERIALS	
Resin (mold)	Epoxy	
Bonding Wire	Ø25µm Au	
Lens color	Water Transparent	
Dice	Red	GaAlAs
	Infrared	GaAlAs

### NOTES:

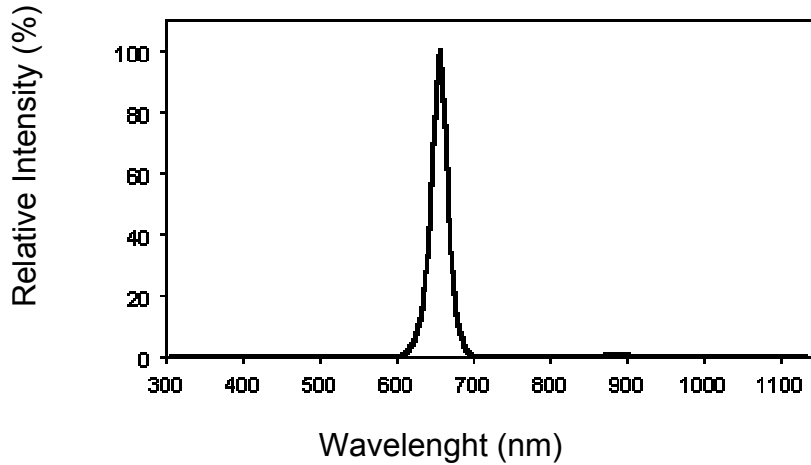
- All dimensions are in millimeters (inches);
- Tolerance are  $\pm 0.2\text{mm}$  (0.008inch) unless otherwise noted.

<b>Absolute maximum ratings</b>							<b>(T<sub>A</sub>=25°C)</b>	
Parameter	Symbol	Value			Unit			
		R	IR					
Power dissipation	Pd	69	90		mW			
Forward current	If	30	50		mA			
Reverse voltage	Vr	5			V			
Operating temperature range	Top	-20 ~+80			°C			
Storage temperature range	Tstg	-20~+80			°C			
Peak pulsing current (1/8 duty f=1kHz)	Ifp	125			mA			
Peak forward current of Infrared 1/100 duty,Pulse width 100µs	Ifp	1			A			
<b>Electro-optical characteristics</b>							<b>(T<sub>A</sub>=25°C)</b>	
Parameter	Test Condition	Symbol	Value			Unit		
			Min	Typ	Max			
Wavelength at peak emission	If=20mA	λ peak	R	650	660	670	nm	
			IR	--	940	--		
Spectral half bandwidth	If=20mA	Δλ	R	--	20	--	nm	
			IR	--	50	--		
Dominant wavelength	If=20mA	λ dom	R	--	640	--	nm	
			IR	--	--	--		
Forward voltage	If=20mA	Vf	R	--	1.8	2.3	V	
			IR	--	1.3	1.8		
Luminous intensity * 1	If=20mA	Iv	R	35	40	--	mcd	
			IR	0.5	0.6	--		
Viewing angle at 50% Iv	If=10mA	2θ 1/2	--	120	--	Deg		
Reverse current	Vr=5V	Ir	--	--	10	µA		
Chromaticity Coordinates	If=20mA	X	--	0.	--	Red		
		Y	--	0.	--			
Chromaticity Coordinates	If=20mA	X	--	0.	--	Yellow		
		Y	--	0.	--			

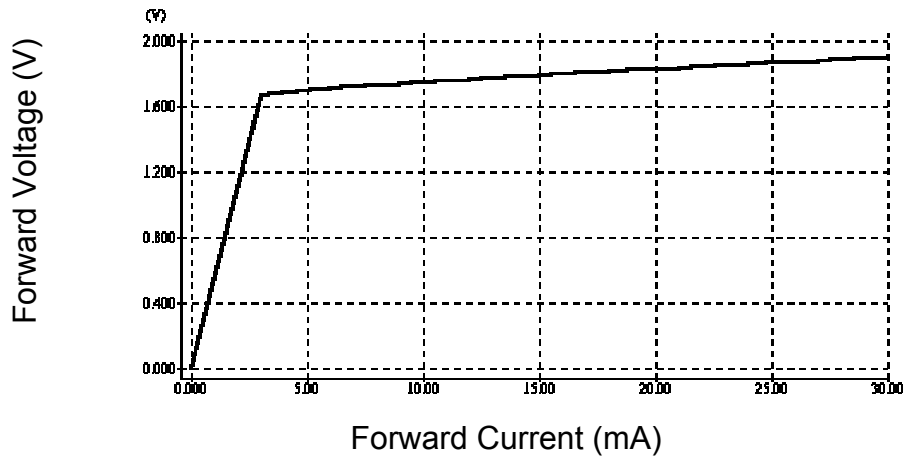
\* 1 Note: Luminous intensity tolerance is ±10%.

## OPTICAL CHARACTERISTIC CURVES (Red)

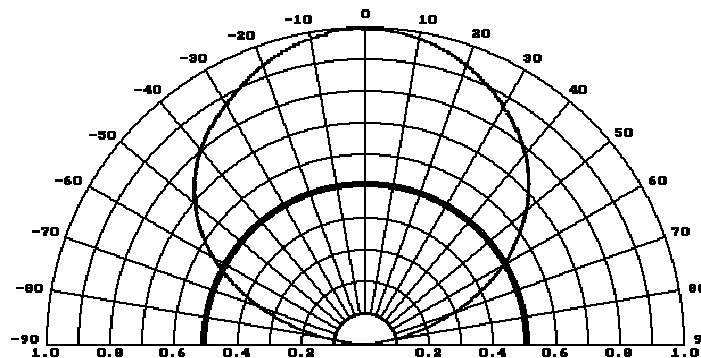
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage

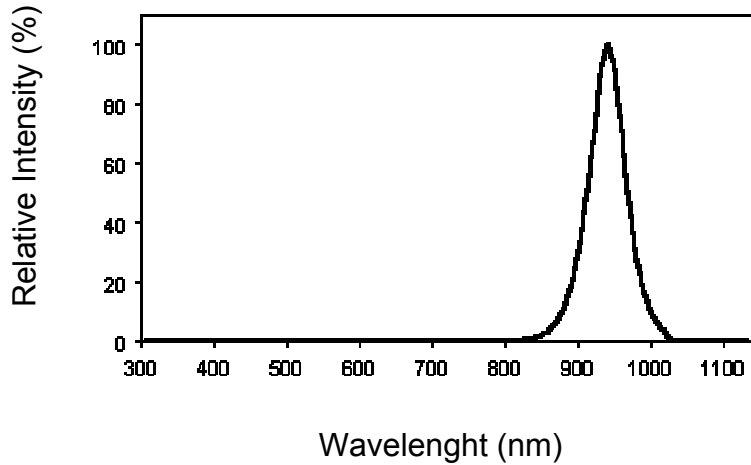


Directive Characteristics

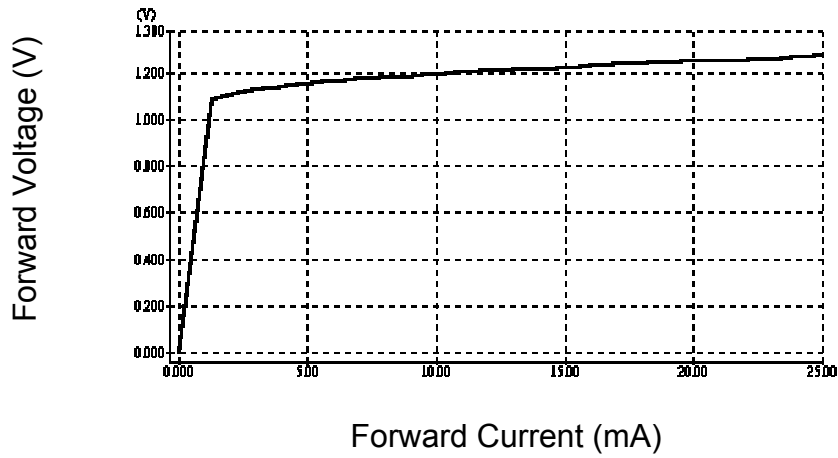


## OPTICAL CHARACTERISTIC CURVES (Infrared)

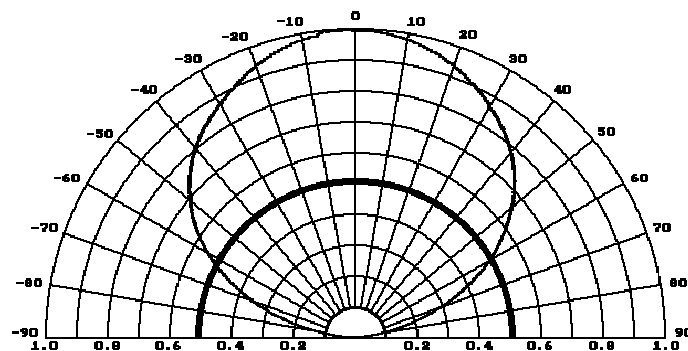
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage

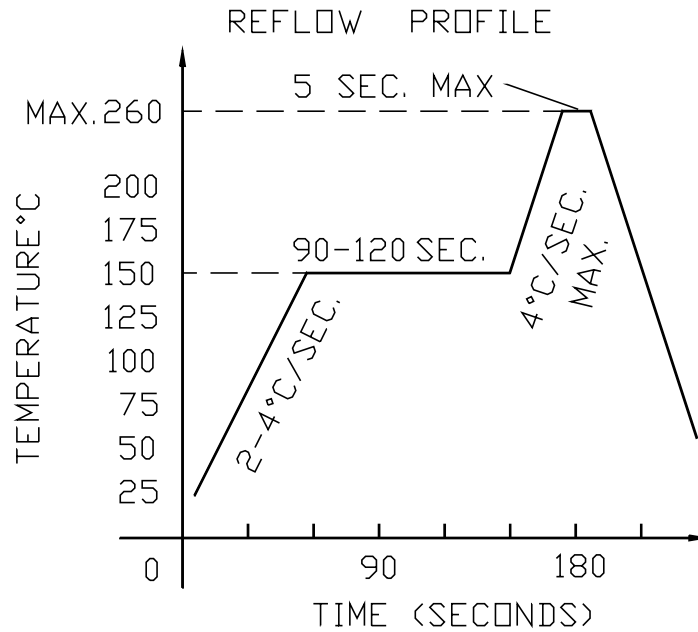


Directive Characteristics



# Reflow Profile

## ■ Reflow Temp/Time

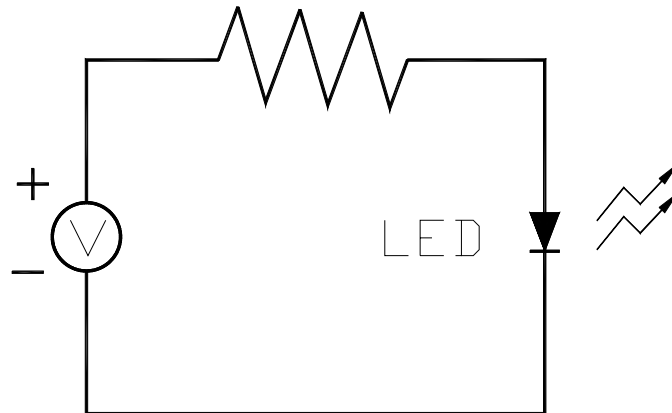


## ■ Soldering iron

Basic spec is  $\leq 5\text{sec}$  when  $260^{\circ}\text{C}$ . If the temperature is higher, time should be shorter ( $+10^{\circ}\text{C} \rightarrow -1\text{sec}$ ). Power dissipation of iron should be smaller than 15W, and temperatures should be controllable. Surface temperature of the device should be under  $230^{\circ}\text{C}$ .

## Test circuit and handling precautions

### ■ Test circuit



### ■ Handling precautions

#### 1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

#### 2. Storage

2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature : 5°C~30°C (41°F~86°F)

2.2 Shelf life in sealed bag: 12 month at < 5°C~30°C and < 30% R.H. after the package is

Opened, the products should be used within a week or they should be keeping to storage at  $\leq 20$  R.H. with zip-lock sealed.

#### 3. Baking

It is recommended to backing before soldering when the pack is unsealed after 72hrs. The Conditions are as followings:

3.1  $60 \pm 3^\circ\text{C}$  x(12~24hrs) and < 5%RH, taped reel type

3.2  $100 \pm 3^\circ\text{C}$  x(45min~1hr), bulk type

3.3  $130 \pm 3^\circ\text{C}$  x(15~30min), bulk type

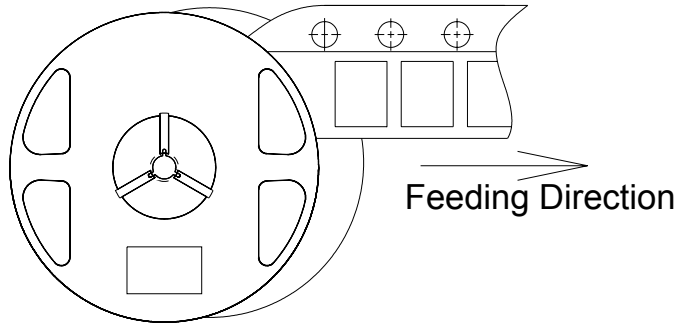
When you discover that the desiccant in the package has a pink color (normal=blue), you Should treat them in the same conditions as (3.1~3.3)

## Test items and results of reliability

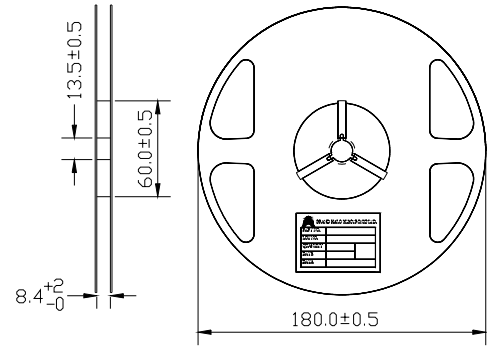
Type	Test Item	Test Conditions	Note	Number of Damaged
Environmental Sequence	Temperature Cycle	-20°C 30min ↑ ↓ 80°C 30min	100 cycle	0/22
	Thermal Shock	-20°C 15min ↑ ↓ 80°C 15min	100 cycle	0/22
	High Humidity Heat Cycles	30°C ↔ 65°C 90%RH 24hrs/1cycle	10 cycle	0/22
	High Temperature Storage	T <sub>a</sub> =80°C	1000 hrs	0/22
	Humidity Heat Storage	T <sub>a</sub> =60°C RH=90%	1000 hrs	0/22
	Low Temperature Storage	T <sub>a</sub> =-30°C	1000 hrs	0/22
Operation Sequence	Life Test	T <sub>a</sub> =25°C I <sub>f</sub> =20mA	1000 hrs	0/22
	High Humidity Heat Life Test	60°C RH=90% I <sub>f</sub> =20mA	500 hrs	0/22
	Low Temperature Life Test	T <sub>a</sub> =-20°C I <sub>f</sub> =20mA	1000 hrs	0/22

## Multi-Color High Performance SMD Chip LED Lamps Packaging Specifications

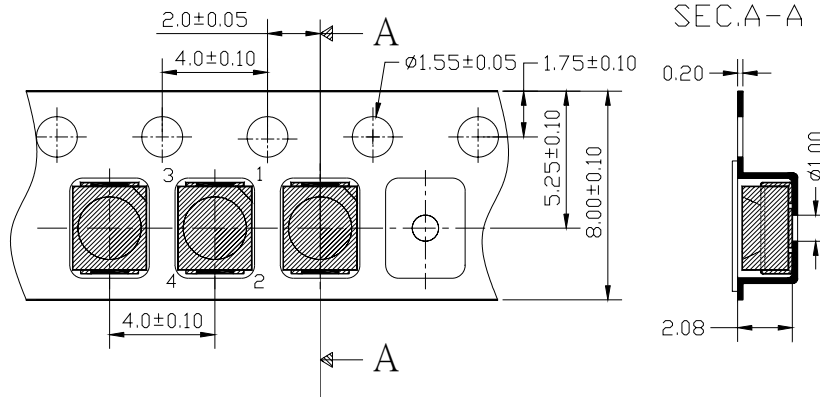
### ● Feeding Direction



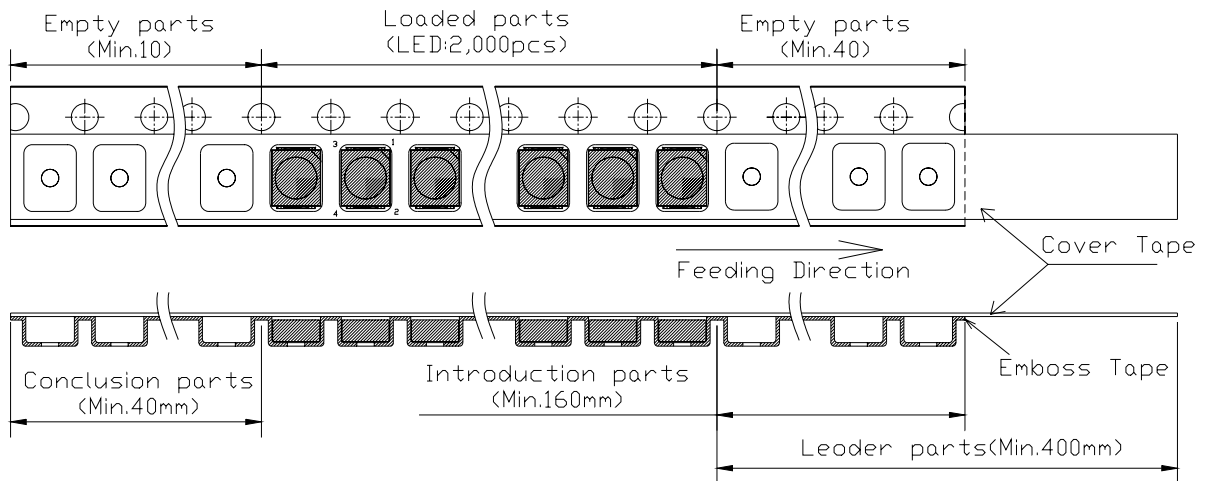
### ● Dimensions of Reel (Unit: mm)



### ● Dimensions of Tape (Unit: mm)



### ● Arrangement of Tape



### NOTES

1. Empty component pockets are sealed with top cover tape;
2. The maximum number of missing lamps is two.
3. 2,000 pcs/Reel